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SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a semiconductor device used for an electronic equipment and particularly to the semiconductor device having a resistor and a manufacturing method therefor.

2. Description of the Related Art

Conventionally, the resistor made of a polycrystalline silicon film is manufactured by depositing the polycrystalline silicon film on a silicon substrate whose surface is oxidized or the like to form an insulating film, implanting in the polycrystalline silicon an impurity such as boron difluoride or phosphorous, and then etching the polycrystalline silicon into the resistor using a photoresist or the like as a mask. Fig. 3 is a plan view showing a polycrystalline silicon film resistor. An amount of the impurity implanted into a polycrystalline silicon film resistor 103 is determined by determining a length L 101 and a width W 102 thereof and then performing calculation using the length L 101 and the width W 102 of the polycrystalline silicon film resistor and a desired resistance value.

However, in recent years, high accuracy is required for the semiconductor device. The polycrystalline silicon film resistor manufactured by using a conventional manufacturing method involves

a variation in resistance value, which prevents improvement in performance of the semiconductor device mounting the polycrystalline silicon film resistor therein, in particular, the semiconductor device for which absolute value accuracy of the resistor is required as in an A/D converter or the like.

SUMMARY OF THE INVENTION

The present invention has been made in view of the above-mentioned problem and an object of the present invention is to provide a semiconductor device capable of solving the above-mentioned problem, which includes a polycrystalline silicon film resistor having a reduced variation in resistance value with high accuracy, and to provide a manufacturing method therefor.

In order to achieve the above object, the present invention employs a means as described below.

The present invention employs a means for using an implantation amount of an impurity implanted into the polycrystalline silicon film resistor around the impurity implantation amount in which a sheet resistance value becomes minimum when manufacturing the polycrystalline silicon film resistor.

As a result of trial manufacturing of the present invention, as shown in Fig. 1, it is confirmed that the sheet resistance value of the polycrystalline silicon film resistor takes a minimum value

with respect to a certain impurity implantation amount. The fact that there exists a minimum value of the sheet resistance value with respect to the impurity implantation amount means that even if the impurity implantation amount varies in the vicinity of the minimum value of the sheet resistance, the variation in sheet resistance value is kept small.

In the case where the impurity implantation amount is previously determined, in order to obtain a desired resistance value for the polycrystalline silicon film resistor, a relation may be utilized, which is expressed by the following equation:

$$R = \rho_s \times L/W$$

where

R indicates the resistance value of the polycrystalline silicon film resistor,

ρ_s indicates the sheet resistance value of the polycrystalline silicon film resistor,

L indicates a length of the polycrystalline silicon film resistor, and

W indicates a width of the polycrystalline silicon film resistor.

When the impurity implantation amount is determined, the sheet resistance value of the polycrystalline silicon film resistor is determined. Thus, L/W, that is, the length and the width of the

polycrystalline silicon film resistor may be determined so as to obtain the desired resistance value of the polycrystalline silicon film resistor.

With the above-mentioned structure, the polycrystalline silicon film resistor with a small variation can be obtained.

BRIEF DESCRIPTION OF THE DRAWINGS

In the accompanying drawings:

Fig. 1 shows a dependence of a sheet resistance value on an impurity implantation amount in a polycrystalline silicon film resistor;

Figs. 2A to 2E are schematic sectional views taken along the line A-A' of Fig. 3, which show the polycrystalline silicon film resistor in a manufacturing order (Embodiment 1 of the present invention); and

Fig. 3 is a plan view showing the polycrystalline silicon film resistor.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

Hereinafter, a description will be made of an embodiment of the present invention.

Embodiment 1 will be described with reference to Fig. 1.

Fig. 1 shows a result of trial manufacturing by the inventor of the present invention. This shows a dependence of a sheet

resistance value on an impurity implantation amount when in a polycrystalline silicon film with a thickness of 1000 Å, boron difluoride is implanted through ion implantation at 50 KeV. When a dose amount of the boron difluoride is $3.0 \times 10^{15} \text{ cm}^{-2}$, the sheet resistance value takes $0.4 \text{ K}\Omega/\text{square}$ as a minimum value. Thus, in the case where the boron difluoride is implanted through impurity implantation at 50 KeV to form the polycrystalline silicon film resistor, the impurity implantation amount of the boron difluoride is set to $3.0 \times 10^{15} \text{ cm}^{-2}$.

At this time, if the polycrystalline silicon film resistor of $1 \text{ K}\Omega$ is formed, since $1\text{K} = 0.4 \text{ K} \times L/W$, L/W is selected such that a ratio of L to W satisfies 5:2. For example, L/W is set to 20/8 or 40/16. The polycrystalline silicon film resistor is formed as in this embodiment, so that the polycrystalline silicon film resistor with a small variation in resistance value can be manufactured.

When the semiconductor device is manufactured on a silicon substrate, a plurality of identical semiconductor devices are formed on the same silicon substrate in many cases. In the case where the impurity implantation amount of the boron difluoride is set to $3.0 \times 10^{15} \text{ cm}^{-2}$, even if the impurity implantation amount of the boron difluoride supposedly varies in a range from $2.0 \times 10^{15} \text{ cm}^{-2}$ to $4.0 \times 10^{15} \text{ cm}^{-2}$, it is possible to suppress the variation in sheet resistance value of the polycrystalline silicon film resistor

to about 10% or less.

Hereinafter, a description will be given of a manufacturing method when the polycrystalline silicon film resistor of $1\text{K}\Omega$ is manufactured through ion implantation of the boron difluoride.

The manufacturing method for the polycrystalline silicon film resistor will be described using Figs. 2A to 2E each corresponding to a section taken along the line A-A' of Fig. 3.

As shown in Fig. 2A, a surface of a silicon substrate 1 is oxidized by 8000 Å to form a silicon oxide film 2 and then a polycrystalline silicon film 3 is deposited thereon by about $0.1\text{ }\mu\text{m}$.

Subsequently, in the polycrystalline silicon film 3, the boron difluoride is implanted at energy of 50 KeV in an implantation amount of $3.0 \times 10^{15}\text{ cm}^{-2}$ through ion implantation.

As shown in Fig. 2B, the polycrystalline silicon film 3 deposited on the substrate surface changes into a polycrystalline silicon film (after implantation of the boron difluoride) 5 having a sheet resistance value of $0.4\text{ K}\Omega/\text{square}$.

By using photolithography, a photoresist 4 is patterned into a resistor on the polycrystalline silicon film (after implantation of the boron difluoride) 5. Fig. 2C is a sectional view showing a state at this stage. At this time, patterning is performed such that a length L of a polycrystalline silicon film resistor 6 is $40\text{ }\mu\text{m}$ and a width W thereof is $16\text{ }\mu\text{m}$.

Fig. 2D shows a state in which etching is performed on the polycrystalline silicon film (after implantation of the boron difluoride) 5 and then the resist is peeled off.

Thereafter, non-doped silicate glass 8 (hereinafter, referred to as an NSG film) with a thickness of 0.3 μm and boronphosphosilicate glass 7 (hereinafter, referred to as a BPSG film) with a thickness of 0.5 μm are deposited, followed by annealing at 900 °C and forming a contact portion 11 for leading out an electrode through etching. As metal used for a wiring, Ti, TiN, and Al-Si-Cu are deposited with a thickness of 0.05 μm , 0.15 μm , and 0.9 μm , respectively. Then, patterning is performed to form the wiring. A plasma nitride film 9 is deposited with a thickness of 1 μm as a protective film, followed by a step of forming a pad portion for leading out the electrode through etching to thereby complete the polycrystalline silicon film resistor. Fig. 2E is a sectional view taken along the line A-A' of Fig. 3 at the time of completion.

According to the present invention, when the polycrystalline silicon film resistor is manufactured, it is possible to suppress to a minimum value the variation in sheet resistance value thereof caused by a variation in impurity implantation amount. The variation in sheet resistance value of the polycrystalline silicon film resistor is suppressed to a minimum value, whereby the semiconductor device mounting the resistor with high accuracy can

be provided.

WHAT IS CLAIMED IS:

1. A semiconductor device comprising a polycrystalline silicon film resistor that is formed by implanting an impurity into a polycrystalline silicon film deposited on a semiconductor substrate,

wherein the polycrystalline silicon film resistor has a concentration of the impurity implanted in an amount set in proximity to an impurity implantation amount in which a sheet resistance value becomes minimum.

2. A manufacturing method for a semiconductor device that includes a polycrystalline silicon film resistor formed by implanting an impurity into a polycrystalline silicon film deposited on a semiconductor substrate,

comprising a step of implanting the impurity in the polycrystalline silicon film resistor in an amount set in proximity to an impurity implantation amount in which a sheet resistance value becomes minimum.

3. A semiconductor device according to Claim 1, comprising a polycrystalline silicon film resistor that is formed by implanting an impurity into a polycrystalline silicon film deposited on a semiconductor substrate,

wherein the polycrystalline silicon film resistor has a

length and a width of the resistor so as to obtain a desired resistance value.

4. A manufacturing method for a semiconductor device according to Claim 2, which includes a polycrystalline silicon film resistor formed by implanting an impurity into a polycrystalline silicon film deposited on a semiconductor substrate,

further comprising a step of forming the polycrystalline silicon film resistor with a length and a width of the resistor so as to obtain a desired resistance value.